

CoreFocus
Report
No.383

GCMS

FID

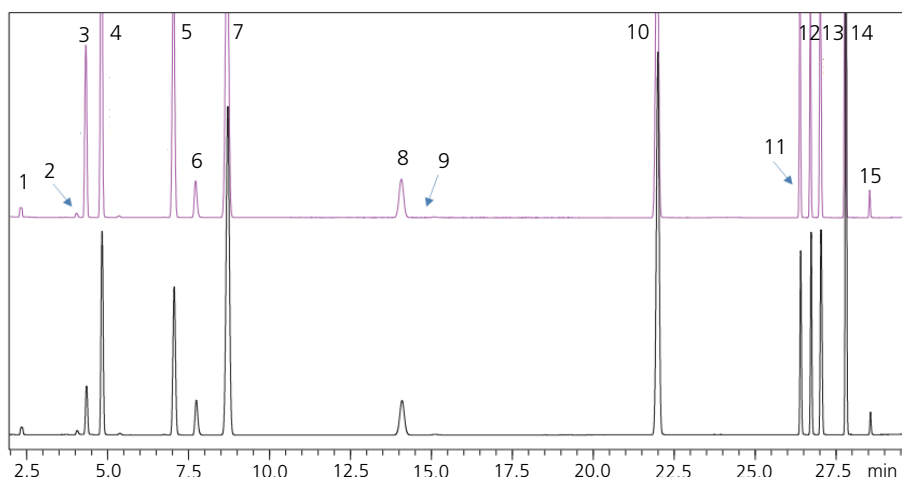
HS

SH Series

SH-I-624Si MS

Analysis of Residual Solvents in Pharmaceuticals

Keywords: Headspace



1. Methanol
2. Acetonitrile
3. Methylene Chloride
4. *trans*-1,2-Dichloroethene
5. *cis*-1,2-Dichloroethene
6. Tetrahydrofuran
7. Cyclohexane
8. Methylcyclohexane
9. 1,4-Dioxane
10. Toluene
11. Chlorobenzene
12. Ethylbenzene
13. *m,p*-Xylene
14. *o*-Xylene
15. Cumene

Model : GCMS-QP™2020/HS-20/FID-2010 Plus
Splitting System

HS

Mode : Loop (volume 1 mL)
Oven temp. : 80 °C
Sample line temp. : 90 °C
Transfer line temp. : 105 °C
Gas pressure : 76.4 kPa
for vial pressurization
Vial equilibrating time : 45 min
Vial pressurizing time : 2.0 min
Pressure equilibrating time : 0.1 min
Load time : 0.5 min
Load equilibrating time : 0.1 min
Injection time : 0.5 min
Needle flushing time : 15.0 min
APC pressure : 20 kPa

GC

Column : SH-I-624Si MS (30 m x 0.32 mm I.D., 1.8 µm)
P/N : 227-36077-01
Injection mode : Split (Split ratio 1:5)
Control mode : Constant pressure (89.4 kPa)
Carrier gas : He
Oven temp. : 40 °C (20 min) - 10 °C/min - 240 °C (20 min)
Restrictor (FID) : 1.1 m x 0.25 mm
Restrictor (MS) : 1.5 m x 0.20 mm
APC pressure : 20 kPa

FID

Temp. : 250 °C
Make-up flow rate : 30 mL/min (He)
Hydrogen flow rate : 40 mL/min
Air flow rate : 400 mL/min

MS

Ion source temp. : 200 °C
Interface temp. : 250 °C
SCAN range : *m/z* 29 to 250
Event time : 0.3 s

Source : Application News M272 ([JP](#), [ENG](#))

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